

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Error rs
1	BRS	L1	788	257/782.cc1s. or 257/783.cc1s.	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
2	BRS	L2	134	L1 and(die and substrate and adhesive)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
3	BRS	L3	134	L1 and (die and substrate and adhesive)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
4	BRS	L4	1	L3 and (bismaleimide near adhesive)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
5	BRS	L5	1	substrate and die and (bismaleimide with adhesive) and (solder adj mask)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
6	BRS	L6	129	substrate and die and (bismaleimide same adhesive)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
7	BRS	L7	46	substrate and die and (bismaleimide with adhesive)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0
8	BRS	L8	2	L7 and ((prevent or enhance or impove or benefit) with adhesive)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0	0	0

09/19/2001, EAST Version: 1.02.0008

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9 BRS	L9	0	L7 and ((prevent or enhance or improve or benefit) with (bmi or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:29			0
10 BRS	L10	0	L7 and ((prevent or enhance or improve or benefit) same (bmi or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:29			0
11 BRS	L11	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismeleimide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:51			0
12 BRS	L12	8	L11 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
13 BRS	L13	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismalamide))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:50			0
14 BRS	L14	8	L13 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:53			0
15 BRS	L15	247	(adhesive with (bmi or bism\$)) and ((prevent or improve or increase or advantage or benefit))	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:39		Truncation Overflow. Return string from Server is: 5`660354.	1
16 BRS	L16	87	L15 and (die or chip or semiconductor)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:55			0

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BRS	L117	3	(adhesive with (bmi or bism\$)) with (moisture or break\$)	USPAT; US-PGPU; B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:42		Truncation Overflow. Return string from Server is: 5'660354'	1

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
1	BRS	L1	788	257/782.cc1s. or 257/783.cc1s.	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:09			0
2	BRS	L2	134	L1 and(die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:11			0
3	BRS	L3	134	L1 and (die and substrate and adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:11			0
4	BRS	L4	1	L3 and (bismaleimide near adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:15			0
5	BRS	L5	1	substrate and die and (bismaleimide with adhesive) and (solder adj mask)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:19			0
6	BRS	L6	129	substrate and die and (bismaleimide same adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:19			0
7	BRS	L7	46	substrate and die and (bismaleimide with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:25			0
8	BRS	L8	2	L7 and ((prevent or enhance or improve or benefit) with adhesive)	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 12:28			0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
9 BRS	L9	0	L7 and ((prevent or enhance or impove or benefit) with (bmi or bismeleimide))	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0
10 BRS	L10	0	L7 and ((prevent or enhance or impove or benefit) same (bmi or bismeleimide))	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0
11 BRS	L11	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismeleimide))	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0
12 BRS	L12	8	L11 and (die or chip or semiconductor)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0
13 BRS	L13	16	adhesive and ((prevent or enhance or improve or benefit) same (bmi or bismalamide))	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0
14 BRS	L14	8	L13 and (die or chip or semiconductor)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	Truncation Overflow. Return string from Server is: 5.660354. 0
15 BRS	L15	247	(adhesive with (bmi or bism\$)) and (prevent or impove or increase or advantage or benefit)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0
16 BRS	L16	87	L15 and (die or chip or semiconductor)	US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	USPAT; US-PGPU B; EPO; JPO; DERWENT ; IBM TDB	0 0 0

Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17 BRS	L17	3	(adhesive with (bmi or bism\$)) with (moisture or break\$)	USPAT; US-PGPU; EPO; JPO; DERWENT ; IBM TDB	2001/09/19 13:42		Truncation Overflow. Return string from Server is: 5`660354`	1
18 BRS	L18	25	257/783.cccls. and (bmi or bism\$)	USPAT	2001/09/19 14:35			0
19 BRS	L19	228	(adesion or adhesive)with (bmi or bism\$)	USPAT	2001/09/19 14:07			0
20 BRS	L20	372	(adhesion or adhesive)with (bmi or bism\$)	USPAT	2001/09/19 14:13			0
21 BRS	L21	88	L20 and semiconductor	USPAT	2001/09/19 14:08			0
22 BRS	L22	44	L20 and mask	USPAT	2001/09/19 14:08			0
23 BRS	L23	273	L20 and (substrate or carrier)	USPAT	2001/09/19 14:33			0
24 BRS	L24	410	(chip or die) and (solder adj mask) and adhesive	USPAT	2001/09/19 14:34			0
25 BRS	L25	61	124 and (bmi or bism\$)	USPAT	2001/09/19 14:35			0